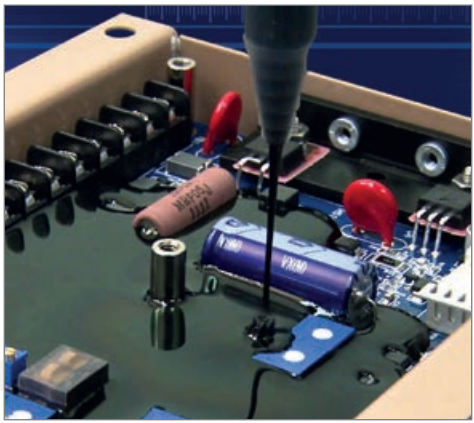
# Epoxy Potting Compounds

## Durapot®

**Electrical and Industrial Applications**



### Performance Chart

| Part Number | Volume Resistance | Thermal Conductivity | Cure Cycle Hours @ | Cure Cycle Minutes @ |
|---|---|---|---|---|
| | Ω-cm | W/m°C | 25°C | |
| 861IP | $10^{13}$ | 0.576 | 16-24 | 5@250°C |
| 862 | $10^{14}$ | 0.576 | 4@120°C | 60@350°C |
| 863 | $10^{14}$ | 1.296 | 4@120°C | 120@350°C |
| 864 | $10^{14}$ | 1.008 | 24 | 120@250°C |
| 865IP | $10^{15}$ | 2.88 | 4-16 | 10@250°C |
| 866 | $10^{15}$ | 0.216 | 24 | 10@250°C |
| 868 | $10^{14}$ | 0.576 | 4@120°C | 60@350°C |

**Notes:**
Post cures at 120°C will improve moisture resistance for Durapot 861, 864, 865 and 866.

### Durapot 861IP
**260°C Low Viscosity Impregnant**
A 100% reactive compound that provides excellent penetration, even in tightly wound coils. Just mix and cure at room temperature to provide excellent electrical, moisture and chemical resistance. Also available in flame retardant grades.

### Durapot 862
**315°C High Temperature Low Viscosity**
High temperature version of 861IP

### Durapot 863
**340°C Ultra High Temperature**
Offers unique properties stemming from a cross-linked, inorganic-organic polymer system. It is a 100% reactive and can be used to 340°C after curing at 175°C. Offers excellent dielectric properties, heat stability, moisture and solvent resistance.

### Durapot 864
**230°C Flexible, Low Viscosity**
Provides the flexibility required for severe thermal shock applications. Bonds to dissimilar materials, including treated Teflon® and other difficult to bond plastics. Has the ability to impregnate and bond thousands of fibre optical strands.

### Durapot 865IP
**260°C Thermally Conductive Compound**
Designed for applications requiring high heat flows and rapid thermal dissipation, excellent chemical resistance and high temperature stability. Used for thermally conductive casting, embedding, impregnating and encapsulation.

### Durapot 866
**260°C Thermally Insulating Compound**
A thermally and electrically insulating compound. Convenient two part, room temperature curing system. Offers a low density, non-porous foam for high temperature applications.

### Durapot 868
**260°C High Temperature & Flexible**
Ideal for thermal shock applications, stress free potting and bonding. Offers high electrical resistance, even at high temperatures up to 260°C.